## Field Stop Trench IGBT 40 A, 650 V

### **Description**

Using the novel field stop 3<sup>rd</sup> generation IGBT technology, AFGHL40T65SPD offers the optimum performance with both low conduction loss and switching loss for a high efficiency operation in various applications, which provides 50 V higher blocking voltage and rugged high current switching reliability.

Meanwhile, this part also offers and advantage of outstanding performance in parallel operation.

#### **Features**

- AEC-Q101 Qualified
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.85 \text{ V (Typ.)} @I_C = 40 \text{ A}$
- 100% Of The Part Are Dynamically Tested (Note 1)
- Short Circuit Ruggedness > 5 μS @ 25°C
- Maximum Junction Temperature: TJ = 175°C
- Fast Switching
- Tight Parameter Distribution
- Positive Temperature Co-efficient for Easy Parallel Operating
- Co-Packed With Soft And Fast Recovery Diode

#### **Typical Applications**

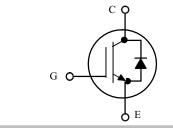
- Onboard Charger
- Air Conditioner Compressor
- PTC Heater
- Motor Drivers
- Other Automotive Power-Train Applications



## ON Semiconductor®

#### www.onsemi.com

V <sub>CES</sub>	E <sub>on</sub>	V <sub>CE(Sat)</sub>
650 V	1.16 mJ	1.85 V





TO-247-3L CASE 340CH

#### **MARKING DIAGRAM**



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = 3-Digit Data code

&K = 2-Digit Lot Traceability code

AFGHL40T65SPD = Specific Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
AFGHL40T65SPD	TO-247-3L	30 Units / Rail

## **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ , Unless otherwise noted)

Symbol	Description	Ratings	Units	
V <sub>CES</sub>	Collector to Emitter Voltage	650	V	
V <sub>GES</sub>	Gate to Emitter Voltage	±20	V	
	Transient Gate to Emitter Voltage	±30	V	
I <sub>C</sub>	Collector Current @ T <sub>C</sub> = 25°C	80	Α	
	Collector Current @ T <sub>C</sub> = 100°C	40		
I <sub>CM</sub>	Pulsed Collector Current (Note 2)	120	Α	
l <sub>F</sub>	Diode Forward Current @ T <sub>C</sub> = 25°C	40	Α	
	Diode Forward Current @ T <sub>C</sub> = 100°C	20		
I <sub>FM</sub>	Pulsed Diode Maximum Forward Current (Note 2)	120	А	
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>C</sub> = 25°C	267	W	
	Maximum Power Dissipation @ T <sub>C</sub> = 100°C	134		
SCWT	Short Circuit Withstand Time @ T <sub>C</sub> = 25°C	5	μs	
$T_J$	Operating Junction Temperature	-55 to +175	°C	
T <sub>stg</sub>	Storage Temperature Range	-55 to +175	°C	
TL	Maximum Lead Temp. For soldering Purposes, 1/8" from case for 5 seconds	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $V_{CC} = 400 \text{ V}$ ,  $V_{GE} = 15 \text{ V}$ ,  $I_{C} = 120 \text{ A}$ ,  $R_{G} = 20 \Omega$ , Inductive Load

2. Repetitive rating: pulse width limited by max. Junction temperature

#### THERMAL CHARACTERISTICS

Symbol	Rating	Max.	Units
$R_{ heta JC}$	Thermal Resistance junction to case, for IGBT	0.31	°C/W
$R_{ heta JC}$	Thermal Resistance junction to case, for Diode	1.19	°C/W
$R_{ heta JA}$	Thermal Resistance junction to Ambient	40	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS				1	l	
Collector-emitter breakdown voltage, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1mA	BVCES	650	_	-	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1mA		-	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V, T <sub>J</sub> = 175°C	ICES	- -	- 750	250 –	μΑ
Gate leakage current, collector- emitter short-circuited	V <sub>GE</sub> = 20 V , V <sub>CE</sub> = 0 V	IGES	-	-	±400	nA
ON CHARACTERISTICS						
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$ , $I_C = 40 \text{ mA}$	VGE(th)	4.0	5.0	7.5	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	VCE(sat)	1.4	1.85 2.51	2.4	V
DYNAMIC CHARACTERISTICS						
Input capacitance		Cies	_	1518	-	
Output capacitance	V <sub>CE</sub> = 30 V, V <sub>GE</sub> = 0 V, f = 1 MHz	Coes	-	91	-	pF
Reverse transfer capacitance		Cres	-	15	-	1
Gate charge total		Qg	-	36	-	nC
Gate to emitter charge	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 40 V, V <sub>GE</sub> = 15 V	Qge	-	11	-	
Gate to collector charge		Qgc	-	12	-	
SWITCHING CHARACTERISTICS						
Turn-on delay time		td(on)	_	18	_	
Rise time	T 0500	t <sub>r</sub>	_	42	-	
Turn-off delay time	$T_C = 25^{\circ}C$ $V_{CC} = 400 \text{ V, } I_C = 40 \text{ A}$	td(off)	-	35	-	ns
Fall time	$Rg = 6 \Omega$	t <sub>f</sub>	-	10	-	
Turn-on switching loss	V <sub>GE</sub> = 15 V	Eon	-	1.16	-	
Turn-off switching loss	Inductive Load, $T_{C} = 25^{\circ}C$	Eoff	-	0.27	-	mJ
Total switching loss		Ets	-	1.43	-	
Turn-on delay time		td(on)	-	16	-	
Rise time		t <sub>r</sub>	-	40	-	
Turn-off delay time	$T_{C} = 175^{\circ}C$ $V_{CC} = 400 \text{ V, I}_{C} = 40 \text{ A}$	td(off)	_	37	-	ns
Fall time	$Rg = 6 \Omega$	t <sub>f</sub>	_	11	-	
Turn-on switching loss	V <sub>GE</sub> = 15 V	Eon	-	1.59	-	
Turn-off switching loss	Inductive Load	Eoff	-	0.42	-	mJ
Total switching loss		Ets	-	2.01	-	1
DIODE CHARACTERISTICS			- I			•
Forward voltage	I <sub>F</sub> = 20 A I <sub>F</sub> = 20 A, T <sub>J</sub> = 175°C	V <sub>F</sub>	1.4	2.2 1.9	2.7 -	V
Reverse Recovery Time	T <sub>J</sub> = 25°C	trr	_	35	-	ns
Reverse Recovery Charge	IF = 20 A, di <sub>F</sub> /dt = 200 A/μs	Qrr	_	58	-	μС

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
DIODE CHARACTERISTICS						
Reverse Recovery Time		trr	-	214	-	ns
Reverse Recovery Charge	T <sub>J</sub> = 175°C IF = 20 A, di <sub>F</sub> /dt = 200 A/μs	Qrr	-	776	-	μC
Reverse Recovery Energy	π = 20 / ξ, αιρ/αι = 200 / ξ μο	Erec	-	51	-	μJ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### TYPICAL PERFORMANCE CHARACTERISTICS

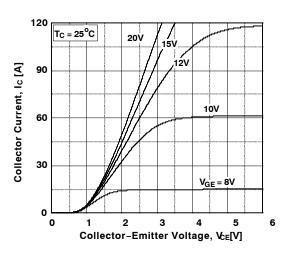


Figure 1. Typical Output Characteristics

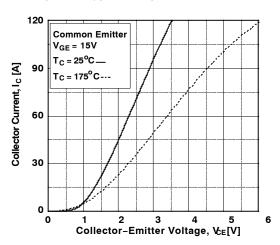


Figure 3. Typical Saturation Voltage Characteristics

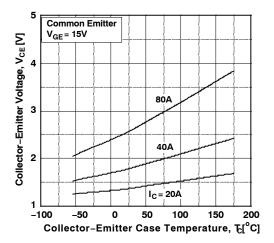


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

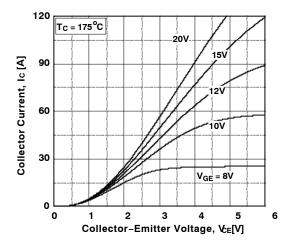


Figure 2. Typical Output Characteristics

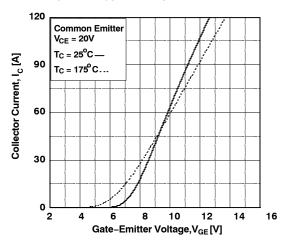
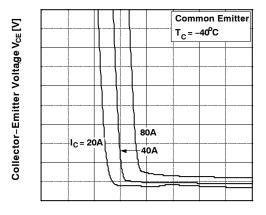


Figure 4. Transfer Characteristics



Gate-Emitter Voltage, V<sub>GE</sub> [V]

Figure 6. Saturation Voltage vs. V<sub>GE</sub>

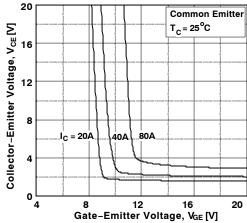


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

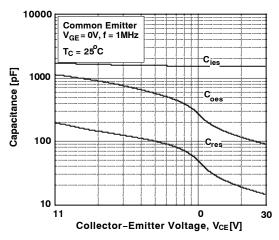


Figure 9. Capacitance Characteristics

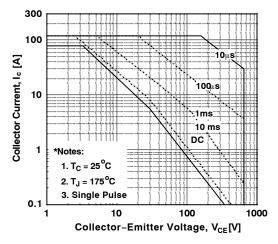


Figure 11. SOA Characteristics

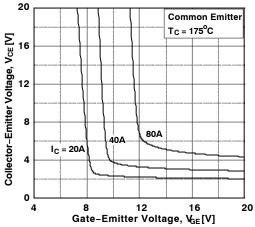


Figure 8. Saturation Voltage vs. V<sub>GE</sub>

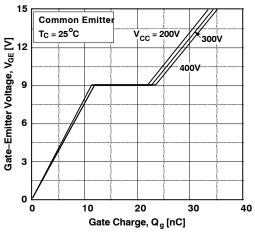


Figure 10. Gate charge Characteristics

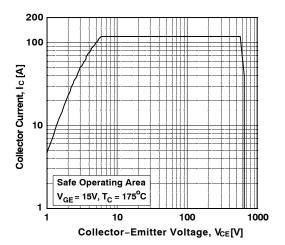


Figure 12. Turn off Switching SOA Characteristics

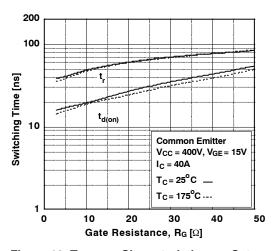


Figure 13. Turn-on Characteristics vs. Gate Resistance

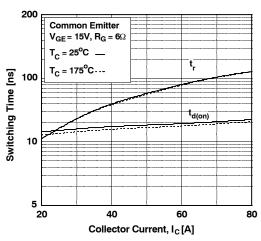


Figure 15. Turn-on Characteristics vs. Collector Current

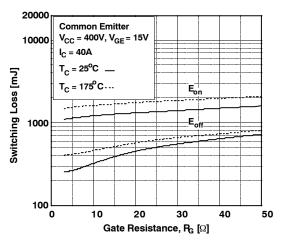


Figure 17. Switching Loss vs Gate Resistance

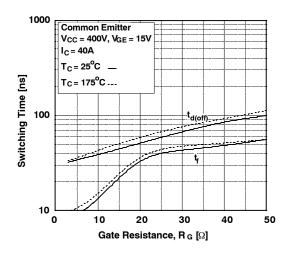


Figure 14. Turn-on Characteristics vs. Gate Resistance

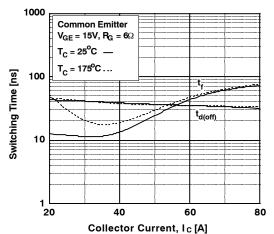


Figure 16. Turn-off Characteristics vs. Collector Current

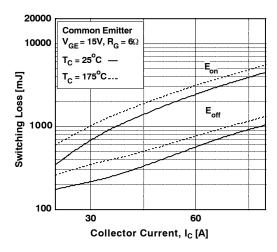


Figure 18. Switching Loss vs Collector Current

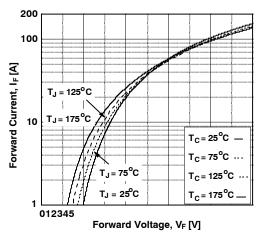


Figure 19. Forward Characteristics

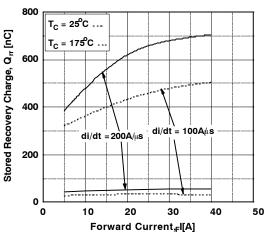


Figure 21. Stored Charge

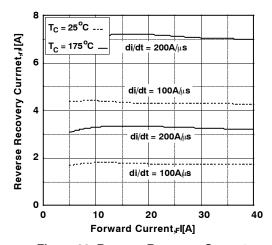


Figure 23. Reverse Recovery Current

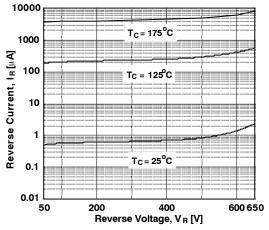


Figure 20. Reverse Current

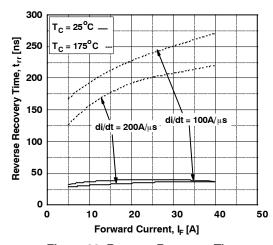


Figure 22. Reverse Recovery Time

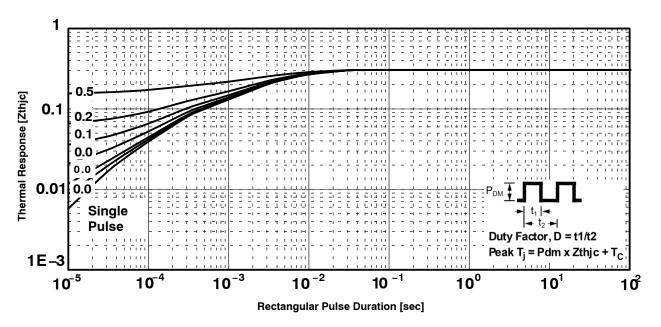
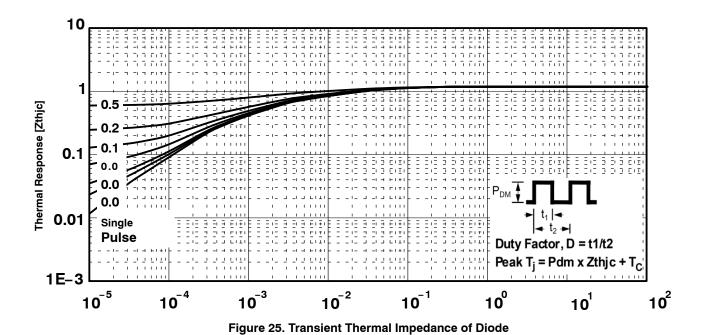
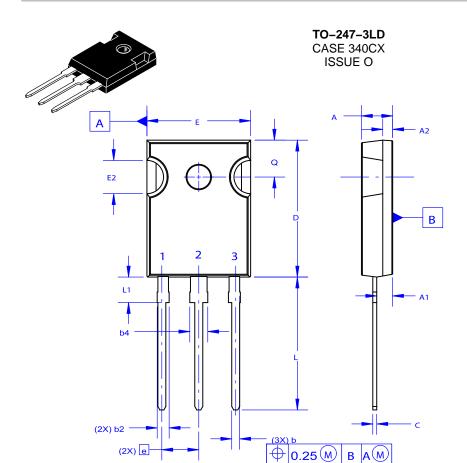
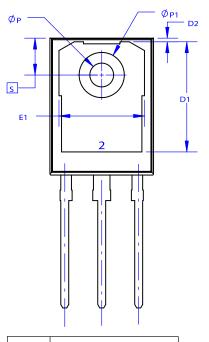


Figure 24. Transient Thermal Impedance of IGBT





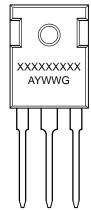
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- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

# GENERIC MARKING DIAGRAM\*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
<b>A</b> 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	?	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
ØP1	6.60	6.80	7.00	

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